

WinhiSemi

VTGA056N18TA

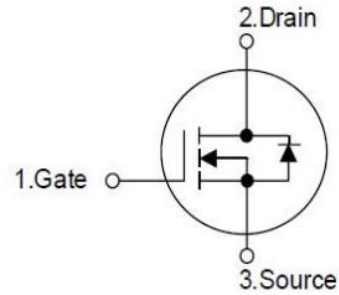
Datasheet

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General Description

VTGA056N18TA N-Channel MOSFET is based on unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics.

Symbol

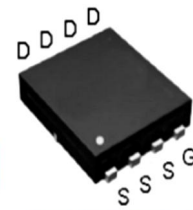


Symbol of VTGA056N18TA

Features

- Low $R_{DS(ON)}$ & FOM
- $R_{DS(ON)_{max}} = 14m\Omega @ V_{GS} = 4.5V$
- Extremely low switching loss
- Fast switching and soft recovery

Package Type



Package Type of VTGA056N18TA

Application

- Charging Circuit
- Battery Applications
- Synchronous Rectification
- High Frequency Switching

Ordering Information

Product Name	Package	Marking
VTGA056N18TA	DFN3*3	56N18

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	16	V
Gate-Source Voltage	V_{GS}	±8	V
Continuous Drain Current ^{Note 1} , $T_C=25^{\circ}C$	I_D	22	A
Pulsed Drain Current ^{Note 2}	I_{DM}	66	A
Max Power Dissipation ^{Note 3} , $T_C=25^{\circ}C$	P_D	19.4	W
Avalanche Current, Single Pulse ^{Note 5}	I_{AS}	22.85	A
Avalanche Energy, Single Pulse ^{Note 5}	E_{AS}	78.3	mJ
Operation Junction temperature	T_J	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		6.45		°C/W
Thermal Resistance, Junction-to-Ambient ^{Note 4}	$R_{\theta JA}$		62		

Notes:

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_D is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25^{\circ}C$.
- 5) $V_{DS}=15V, V_{GS}=4.5V, L=0.3mH, R_g=25\Omega$, starting $T_J=25^{\circ}C$.

Electrical Characteristics (T_J= 25 °C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	16			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =16V, V _{GS} =0V			1	uA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±8V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _D =250uA	0.35	0.55	0.85	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =5A		10.5	13.5	mΩ
		V _{GS} =4.5V, I _D =15A		11	14	mΩ
Gate Resistance	R _G	f=1MHz, open drain		0.72		Ω
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{GS} =0V		1247		pF
Output Capacitance	C _{oss}	V _{DS} =10V		635.3		pF
Reverse Transfer Capacitance	C _{rss}	f=1MHz		312.3		pF
Turn-on Delay Time	t _{d(on)}	V _{DS} =15V		10.2		ns
Rise Time	t _r	V _{GS} =4.5V		3.1		
Turn-off Delay Time	t _{d(off)}	I _D =6A		36.8		
Fall Time	t _f	R _G =3Ω		10.1		
Switching Characteristics						
Total Gate Charge (@V _{GS} =8V)	Q _g	V _{GS} =0 to 8V V _{DS} =10V I _D =15A		28.7		nC
Total Gate Charge (@V _{GS} =4.5V)	Q _g			15.79		
Gate to Source Charge	Q _{gs}			2.2		
Gate to Drain Charge	Q _{gd}			3.66		
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _{SD} =12A		0.81	1.2	V
Reverse Recovery Time	t _{rr}	V _{DS} =10V		33.07		ns
Reverse Recovery Charge	Q _{rr}	I _F =12A		13.79		nC
Peak Reverse Recovery Current	I _{rrm}	di/dt=100A/us		0.56		A

Typical Performance Characteristics

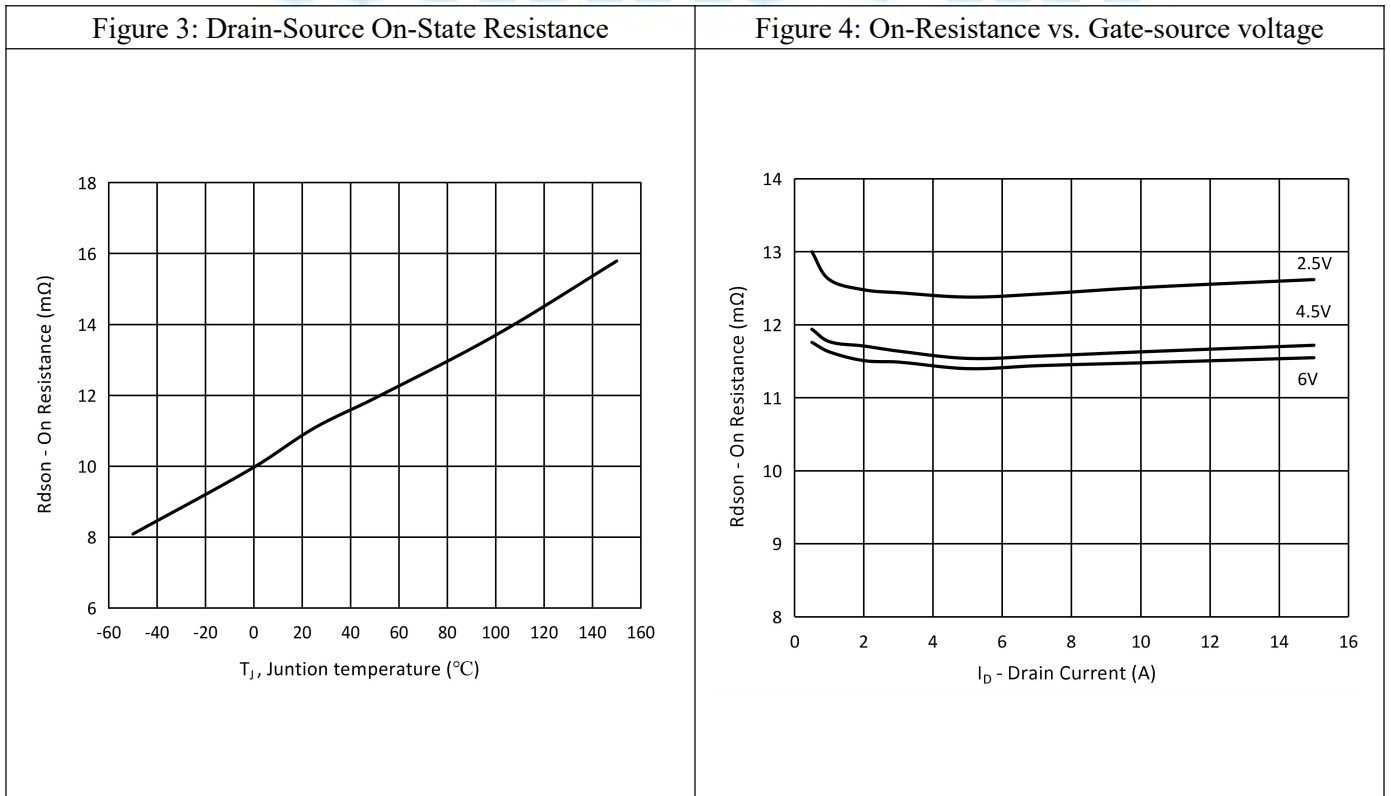
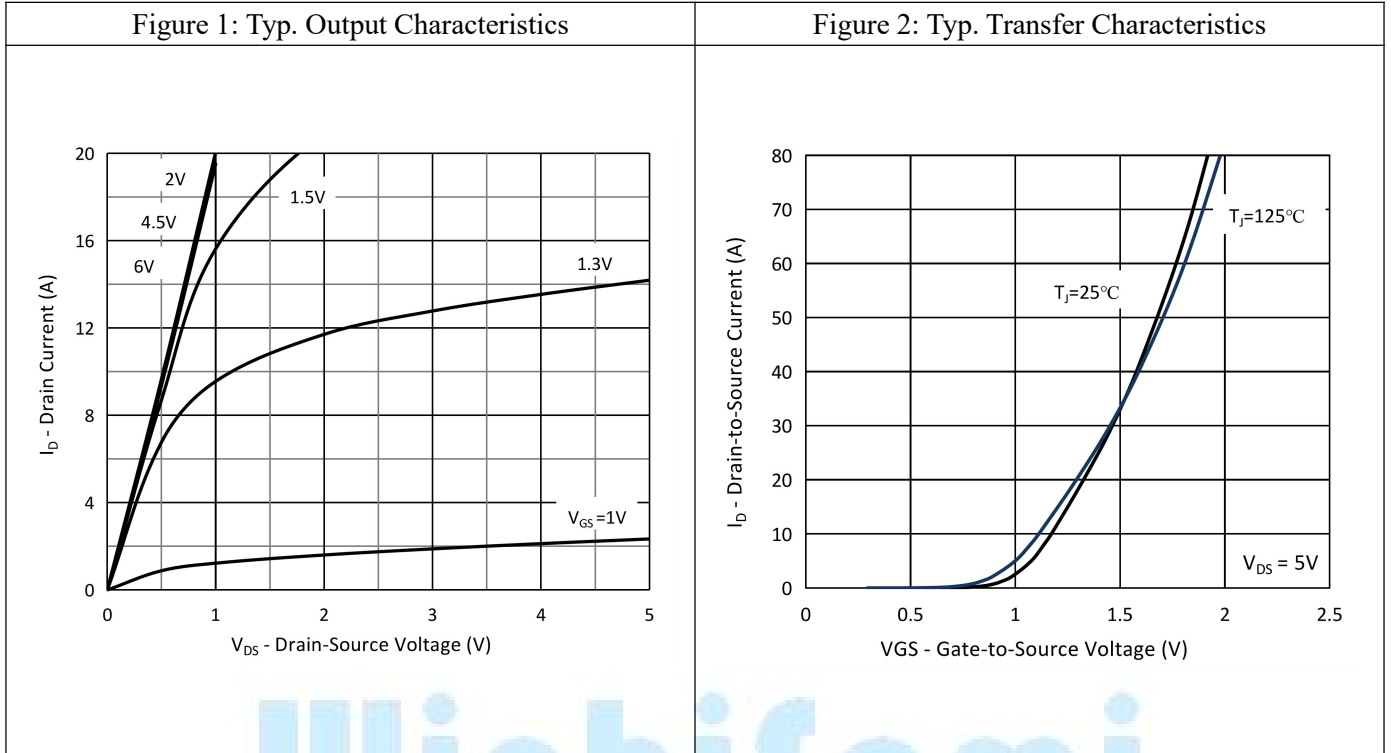


Figure 5: Typ. Capacitances

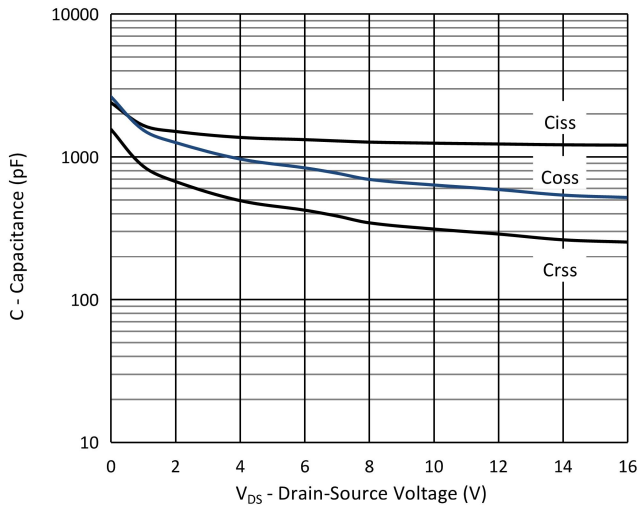


Figure 6: Gate Charge Characteristics

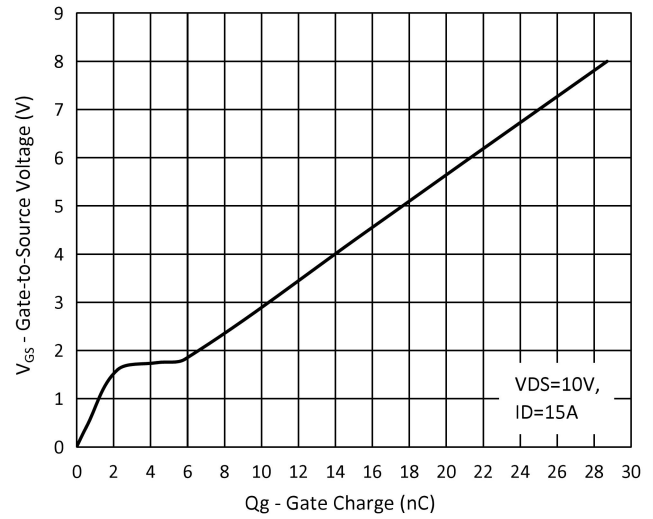


Figure 7: Forward Characteristics of Body Diode

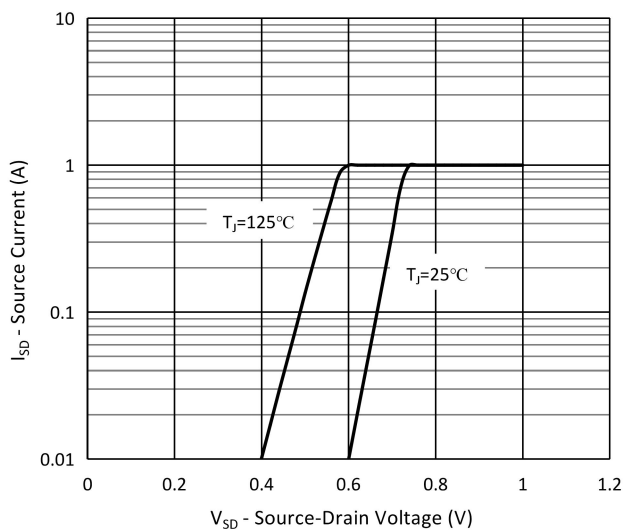


Figure 8: Safe Operating Area T_C=25°C

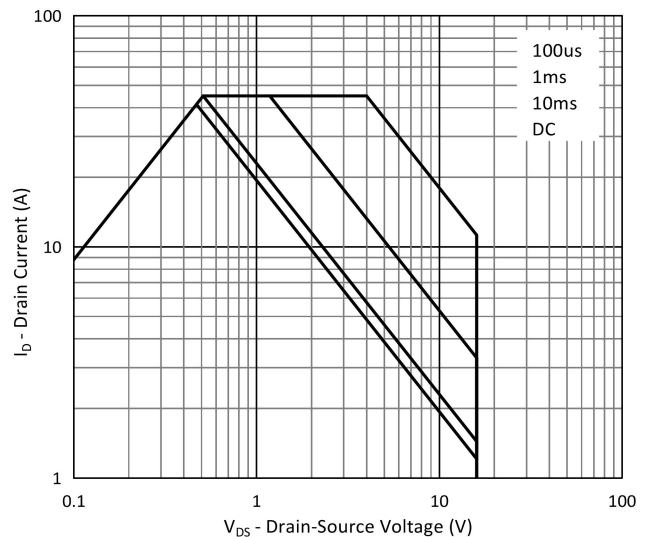


Figure 9: Power De-rating

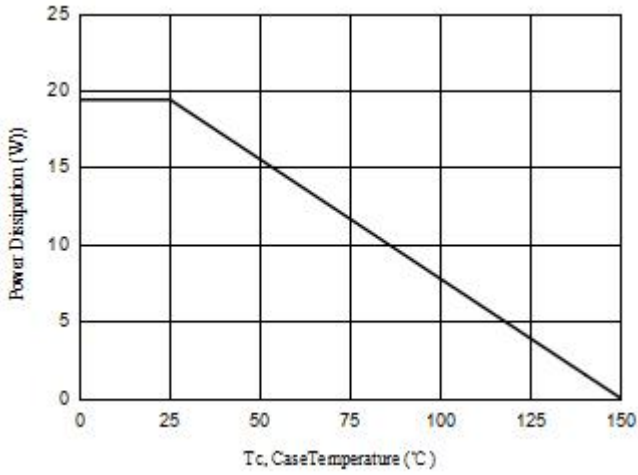


Figure 10: Current De-rating

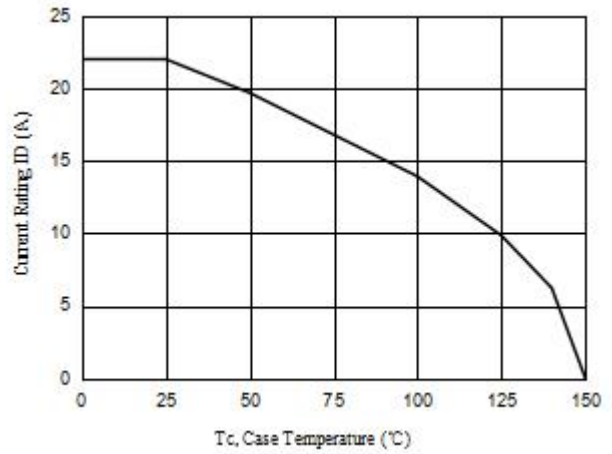


Figure 11: Single pulse power rating, Junction to case

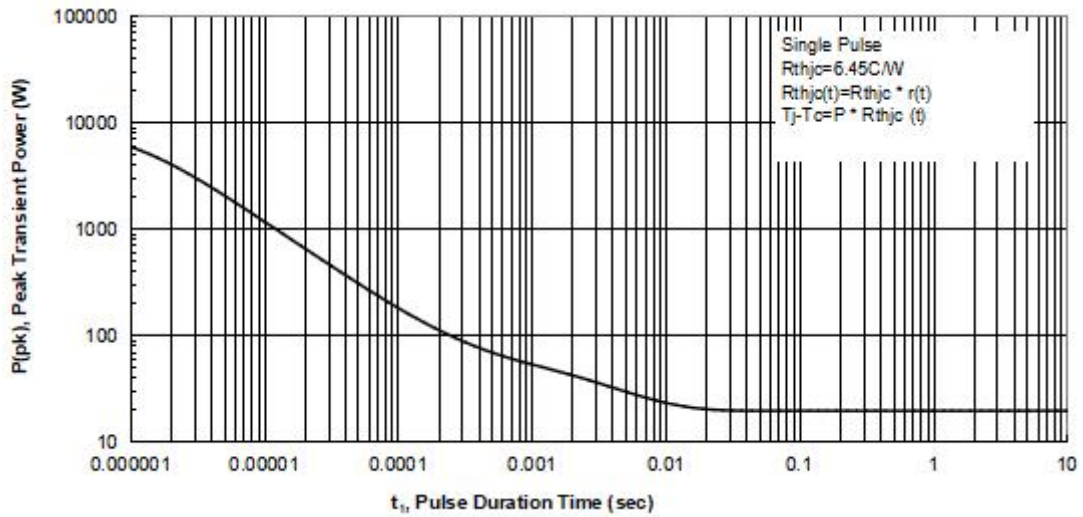
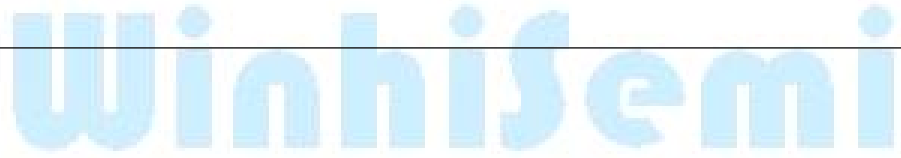
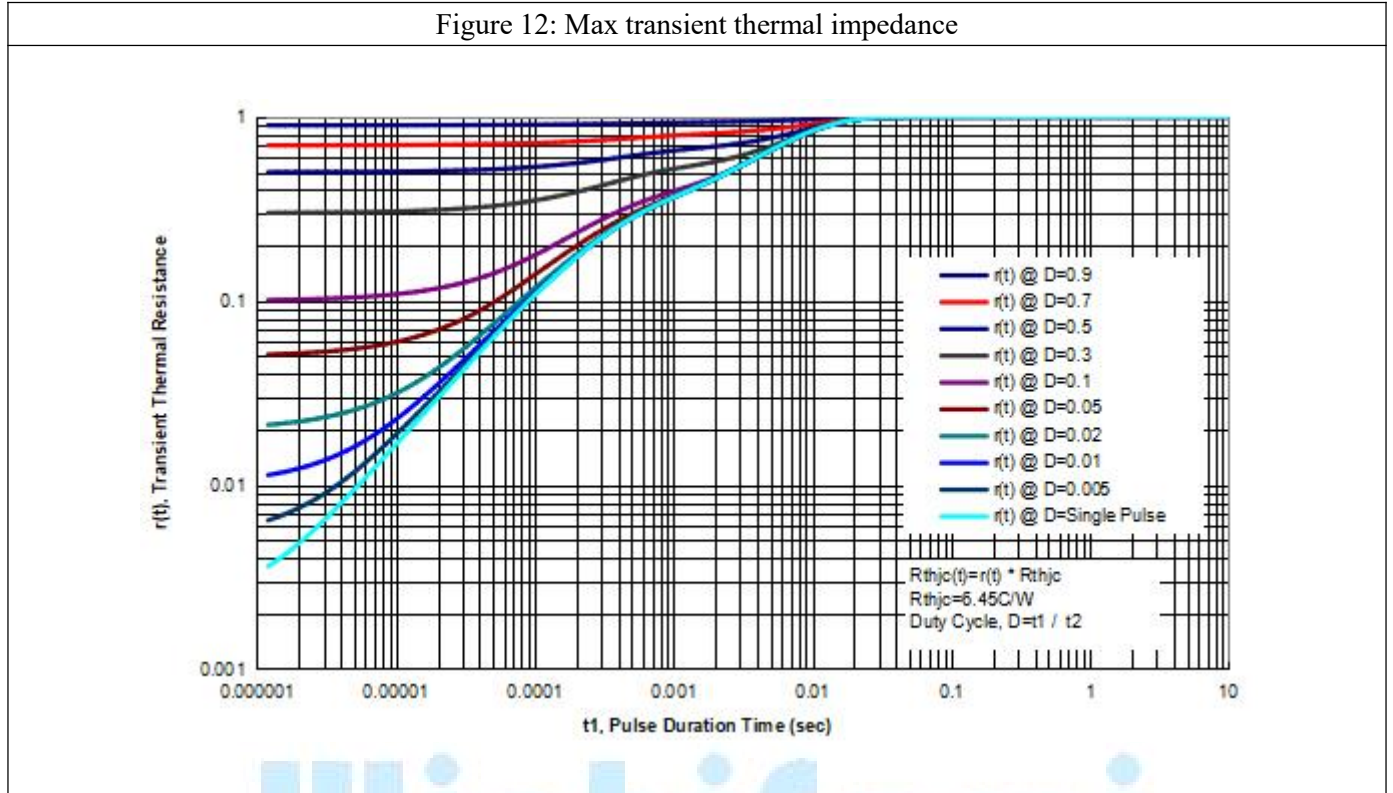
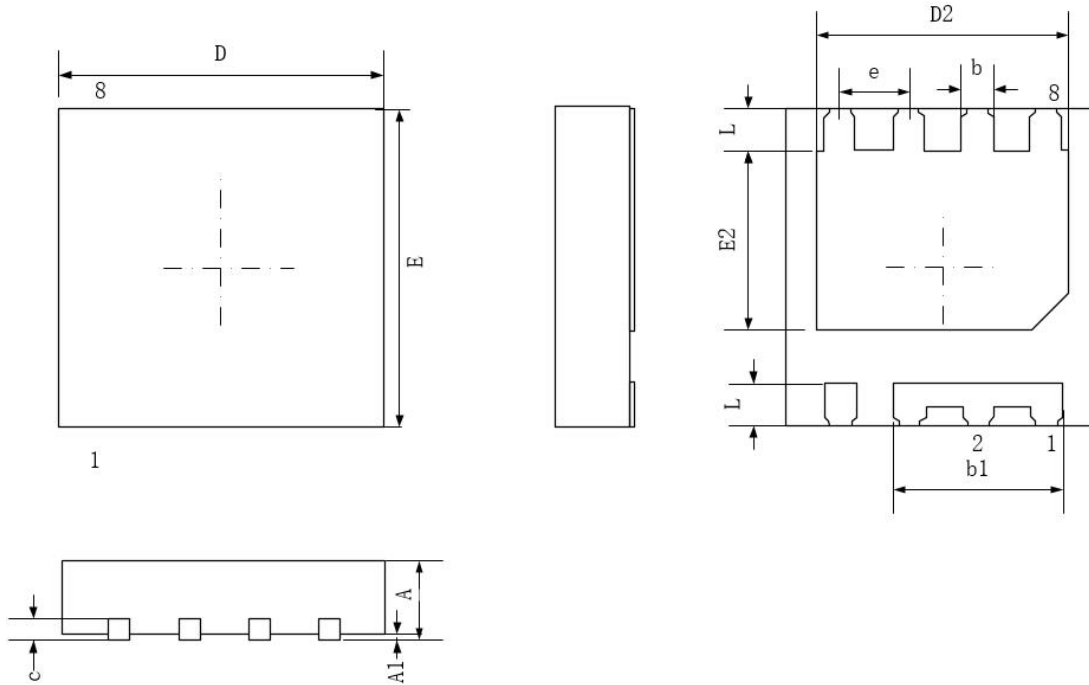


Figure 12: Max transient thermal impedance



Mechanical Dimensions (DFN3*3 Unit:mm)



SYMBOL	MILLMETER		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
b	0.25	0.30	0.35
b1	1.55	1.60	1.65
c	0.19	0.20	0.21
D	2.90	3.00	3.10
D2	2.30	2.40	2.50
E	2.90	3.00	3.10
E2	1.60	1.70	1.80
e	0.65BSC		
L	0.35	0.40	0.45

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